BLDC Motor Driver with Speed Control, Single-Phase, 12 V

LV8316H

Overview

The LV8316H is the driver for a single−phase BLDC motor, which controls motor rotational speed with the built−in closed loop speed controller. Its target speed can be set by input PWM duty cycle. The speed curve setting can be stored to the internal nonvolatile memory (NVM). In addition, Lead−angle can also be adjusted by the configuration saved in the internal NVM. Thus, it can drive various kinds of motors at high efficiency and low noise.

Features

- Single−phase Full Wave Fan Motor Driver, Iomax: 2.0 A
- PWM Duty Cycle Input (25 Hz to 100 kHz)
- PI Closed Loop Speed Control Function
- Soft Start−up Function
- PWM Soft Switching Phase Transitions
- Soft PWM Duty Cycle Transitions (Changing the Target Speed Gradually)
- Built−in Current Limit Circuit Function and Over Current Protection Function
- Built−in Thermal Protection Function
- Built−in Locked Rotor Protection and Automatic Recovery Function
- FG or RD Signal Output Selectable
- Dynamic Lead Angle Adjustment with Respect to Rotation Speed
- Parameter Setting by Serial Communication
- Embedded EEPROM as NVM
- Parameter Setting to the NVM
- Pb−Free and Halogen Free

Typical Applications

- Telecom Server and Base Station Cooling Fan
- Desktop PC Cooling Fan
- Server Cooling Fan
- Refrigerator Circulation Fan
- Appliance Cooling Fan
- Power Supply Unit Cooling Fan

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TSSOP−14 EXPOSED PAD CASE 948AW

XXXX = Specific Device Code

- $A =$ Assembly Location
 $L =$ Wafer Lot
	- $=$ Wafer Lot
- $Y = Year$ W
	- $=$ Work Week
	- = Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

APPLICATION DIAGRAM

Figure 1. Application Diagram

Table 1. EXAMPLE COMPONENT VALUE

VCC and GND (VCC, GND)

The power supplies of the IC need to be decoupled properly. The following three capacitors must be connected.

- between VCC (pin 2 and pin 3) and PGND (pin 13 and pin 14) as C1 in the application diagrams
- between REG (VDD) and SGND as C2

The Zener diode (D2) in Figure 1 is mandatory to prevent the IC break down in case the supply voltage exceeds the absolute maximum ratings due to the flyback voltage.

Hall−Sensor Input Pins (IN1, IN2)

Differential output signals of the hall sensor are connected at IN1 and IN2. It is recommended that the capacitor (C3) is connected between both pins to filter system noise. The value of C3 should be selected properly depending on the system noise. When a Hall IC is used, the output of the Hall

IC must be connected to the IN1 pin and the IN2 pin must be kept in the middle level of the Hall IC power supply voltage which should be corresponded to recommended operating range.

Command Input Pin (PWM)

This pin reads the duty cycle of the PWM pulse which controls rotational speed. The PWM input signal level is supported from 2.8 V to 5.5 V. Linear voltage control is not supported. The minimum pulse width is 100 ns.

Current Limiter Resistor for Hall (R1)

Hall output amplitude can be adjusted by R1.

The amplitude is proportional to Hall bias level VH for particular magnetic flux density. VH is determined by the following equation.

$$
VH = VREG \times \left(\frac{Rh}{Rh + R1}\right) \hspace{1cm} (eq. 1)
$$

Where

VREG: REG pin voltage (5 V) Rh: Hall resistance

However, it should be considered with Hall sensor specification and Hall bias current. The bias current should be set under 20 mA which is REG pin max current.

Table 2. TRUTH TABLE

*Inner PWM state means the OUTPUT active period decided by inner control logic. Don't match with PWM−pin input signal. *Condition: Register "DRVMODE [1:0]" = 01

Table 3. ABSOLUTE MAXIMUM RATINGS

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. IOUT_{MAX} is the peak value of the motor supply current.
2. Specified circuit board: Toroidal shaped. The actual area is 320 mm² and thickness is 0.8 mm, glass epoxy 2–layer board which has 1/2 oz copper traces on top and bottom of the board.

3. Moisture Sensitivity Level (MSL): IPC/JEDEC standard: J−STD−020A

4. For information, please refer to our Soldering and Mounting Techniques Reference Manual, SOLDERRM/D

http://www.onsemi.com/pub_link/Collateral/SOLDERRM−D.PDF

5. ESD Human Body Model is based on JEDEC standard: JESD22−A114

6. ESD Charged Device Model is based on JEDEC standard: JESD22−C101

Table 4. THERMAL CHARACTERISTICS

Table 5. RECOMMENDED OPERATING RANGES

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

7. When the VCC voltage is below 6.0 V, a motor keeps rotation until to 3.9 V, normally. However there are possibility to change the electric characteristics due to low VCC.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

8. When a motor rotates with below 50 rpm (phase change period over 0.3 s), lock protection will works.

9. When a motor can't rotate for 0.7 s after start−up, lock protection will work.

10. When the locked rotor state continues for long time, lock stop period changes as from 5th off time.

Figure 2. Block Diagram

PIN ASSIGNMENT

(Top View)

Table 7. PIN LIST AND FUNCTION

EQUIVALENT CIRCUIT

Figure 3. OUT1 and OUT2 Equivalent Circuit

Figure 4. VCC1,2/PGND1,2/SGND Equivalent Circuit

Figure 7. IN1 Equivalent Circuit **Figure 8. IN2 Equivalent Circuit**

Figure 11. TSL Equivalent Circuit

Figure 5. REG Equivalent Circuit **Figure 6. VDD Equivalent Circuit**

Figure 9. FG Equivalent Circuit **Figure 10. PWM Equivalent Circuit**

OPERATION DESCRIPTION

Soft Start

The LV8316H has various functions and parameters which are defined by built−in registers. Refer to the Register map and description page for the detail.

Spin−up Sequence

To spin−up a motor, power is applied to VCC pin, and the appropriate input PWM signal (see "DUTY_L" and "DUTY S" setting description in section "Steady rotation") is applied to PWM pin. The LV8316H starts driving the motor whose current direction is determined by the Hall sensor signal. To avoid the unnecessary rush current, the "soft start" mode is provided, which gradually increases output duty−cycle. After the soft start mode, LV8316H goes to steady rotation mode. The detail of the soft start mode and steady rotation mode are described in the sections below.

If a motor already rotates at the power on in faster speed than 304 rpm, the soft start mode is skipped and goes to steady rotation mode immediately.

For soft start mode, the duty−cycle ramp up profile is defined by the initial duty−cycle, slope, and exit condition. The initial duty−cycle is fixed and it starts from 4%. The slope is programmable. It is determined by registers "ENDPWM" and "INCTIM". The duty−cycle is increased up to the end duty−cycle "ENDPWM" for duration time "INCTIM". The end duty−cycle is selectable at 24% or 80% (see Table 8). The duration time can be selected from 0.0002 sec to 15.2 sec (see Table 9). The exit condition means it's in the state of either the duty cycle reaching "ENDPWM" or that the rotational speed is reaching the exit target speed specified by the register "RELLEV" (see Table 10). Soft start operation requires at least 8 electrical cycles (4 mechanical cycles in case of 4 poles single phase) independent on the exit condition.

Table 8. SOFT START END DUTY−CYCLE

Table 9. SOFT START DURATION TIME

Table 10. SOFT START EXIT TARGET SPEED

To avoid overshoot at the transition from soft start to the steady rotation mode, the release condition is set to 97% of the target speed in case of RELLEV=0.

Figures [12](#page-9-0) and [13](#page-9-0) show the image of soft start mode.

Figure 12. The Image of Soft Start Exit by End Duty−cycle

As the green curve shown in Figure [12](#page-9-0), the output duty−cycle in the soft start mode starts from 4% of the output duty. Then the output duty−cycle is increased to the end duty−cycle linearly, which is shown by yellow circle. After that, LV8316H goes to the steady rotation mode. Figure [13](#page-9-0)

shows the case which the rotational speed reaches the exit target speed before the output duty−cycle reaches to the exit condition.

Figure 14 is the example of the duration time in case of "ENDPWM $= 0$ ".

Figure 14. Example: The Image of Soft Start Duration Time

Steady Rotation

The rotational speed is controlled by built−in PI closed loop speed control function. The target rotational speed is defined by input PWM pin.

The input PWM frequency range is 25 Hz−100 kHz. The output frequency is fixed to 48 kHz and it is not related to input PWM frequency. Figure 15 shows the speed control profile which is relationship between input PWM duty−cycle and the target rotational speed. Registers to determine this relationship are;

- TAG_L (Address 0x0100 D [7:0]): Minimum target rotational speed
- TAG H (Address 0x0101 D [7:0]): Maximum target rotational speed
- DUTY_L (Address 0x0102 D [7:0]): Minimum input duty−cycle
- DUTY_H (Address 0x0103 D [7:0]): Maximum input duty−cycle
- FULL (Address 0x0109 D [2]): Speed selection at input duty−cycle over DUTY_H
- DUTY S (Address 0x0109 D [3:0]): Speed selection at input duty−cycle under DUTY_L

The detail of each register will be explained later.

Figure 15. Speed Control Profile

TAG_L/TAG_H: Minimum/Maximum Target Rotational Speed Setting

The minimum speed is set by "TAG_L" and the maximum speed is set by "TAG_H" within the range of DUTY_L and DUTY H. (See Figure 16.)

Figure 16. Max/Min Speed Setting

Table [11](#page-12-0) and Table [12](#page-12-0) shows the list of RPM that can be used for speed setting

Do not set the maximum speed setting (TAG_H) less than the minimum speed setting (TAG_L).

Table 11. MINIMUM ROTATIONAL SPEED SETTING TABLE FOR TAG_L

Table 12. MAXIMUM ROTATIONAL SPEED SETTING TABLE FOR TAG_H

DUTY_L/DUTY_H: Minimum/Maximum Input Duty−cycle Setting

The range of PWM input duty−cycle can be set by the registers "DUTY_L" and "DUTY_H" whose range is 0 to 100%. The equation of resolution is

$$
D_{min} = \frac{DUTY_L}{255} \times 100 [%]
$$
 (eq. 2)

$$
D_{max} = \frac{DUTY_H}{255} \times 100 \,\text{[%]} \qquad \qquad \text{(eq. 3)}
$$

Where D_{min} is minimum input duty-cycle

Dmax is maximum input duty−cycle Do not set "DUTY_H" less than "DUTY_L".

Figure 17 shows the relationship between input duty−cycle and target rotational speed. TAG_L/TAG_H define the start and end points of the speed curve and the value between (DUTY_L, TAG_L) and (DUTY_H, TAG_H) are interpolated linearly.

Figure 17. Input Duty−cycle Setting

FULL: Speed Selection at Input Duty−cycle over DUTY_H

For the behavior at input duty−cycle which is over DUTY_H, the register "FULL" provides two options. $FLL = 0$ is to keep the speed specified by "TAG_H" and FULL = 1 is to go to 100% output duty−cycle as shown in Figure 18.

Figure 18. Max Speed Function Setting

DUTY_S: Speed Selection at Input Duty−cycle under DUTY_L

For the behavior at input duty−cycle less than DUTY_L, the register "DUTY_S" provides several options. The "DUTY_S" sets the input duty cycle of the motor speed to 0 rpm. It is calculated by equation 4, except for the case of " $DUTY_S" = 15.$

$$
D_0 = \frac{5 \times DUTY_S}{255} \times 100 \,\text{[%]}
$$
 (eq. 4)

Where D_0 is input duty–cycle of the motor speed 0 rpm Table 13 shows the option of "DUTY−S"

Table 13. THE SETTING OF DUTY_S

DUTY_S	Motor Stop Duty Setting (%)			
0	0			
1	1.9			
2	3.9			
3	5.8			
4	7.8			
5	9.8			
6	11.7			
7	13.7			
8	15.6			
9	17.6			
10	19.6			
11	21.5			
12	23.5			
13	25.4			
14	27.4			
15	The value of DUTY_L			

When $DUTY_S = 15$, the threshold duty–cycle is same as the "DUTY L" setting.

When $DUTY_S = 1$ to 14, the motor speed keeps "TAG_L" setting from "DUTY_L" to "DUTY_S" and goes to 0 rpm at defined by equation 1.

When $DUTY_S = 0$, the motor speed keeps "TAG_L" setting whenever input duty−cycle is less than "DUTY_L".

If "DUTY_L" setting is smaller than "DUTY_S" setting, the threshold is same as "DUTY_L" setting.

To restart the motor rotation, the input duty−cycle must be set higher than "DUTY S" + 1.6% (i.e. the hysteresis is 1.6%).

Figure 19 shows the speed curves for various "DUTY_S".

Output Waveform

The output pulse signal is about $0 V - VCC$ and its duty is controlled by built−in PI closed loop speed control function. The duty before commutation change decreases gradually to 0% and the duty after commutation change increases gradually to the duty level controlled by speed control function by built−in function called Soft Switch. This state is shown in Figure 20 as a schematic view.

Figure 20. Output Waveform Image

Soft Switch Setting

Soft switch width [%] = $\frac{S}{L} \times 100$

The LV8316H can adjust Soft switch period as the ratio of L and S shown in Figure 21. It is defined by following equation and Register "SSWHIGH" and "SSWLOW" can adjust it.

where:

S is Soft Switch period L is one commutation period

Figure 21 shows the soft switch image.

SSWHIGH is for the maximum target rotational speed defined by TAG_H and SSWLOW is for the minimum target rotational speed defined by TAG_L. Each register has 4bits and Table 14 shows the adjustable value.

Table 14. SOFT SWITCH WIDTH ADJUSTMENT

Once "SSWHIGH" and "SSWLOW" is set, the ratio of Soft Start in other speed is interpolated linearly as shown in Figure 22.

FG Output

FG signal output is decided by the Hall signal cross point. The relationship between motor speed and FG frequency represents the following equation.

$$
f_{\mathsf{FG}}[\mathsf{Hz}] = \frac{\mathsf{N}}{60} \times \frac{\mathsf{p}}{2}
$$

Where N: Motor speed [rpm] p: Number of Pole

Figure 23 shows the timing chart of the hall sensor output and the FG output.

Figure 23. Timing Chart of Output

Lead Angle Setting

In the output, the output current delays from the output voltage because of the inductance of motor coil. The output current which flows in a motor coil generates torque for the motor and the torque is maximized by the synchronization of output current with the BEMF phase. Therefore, this delay decreases an efficiency of motor rotation. It is generally increased in proportion to the rotational speed.

The LV8316H can cancel the delay by earlier commutation than the Hall sensor signal as shown in Figure 24. This phase adjustment is called "Lead−angle".

In Figure 24, the output voltage VOUT1 and the output current IOUT1 in black are changed to the waveform in red after the Lead−angle adjustment and it is the most optimum commutation timing.

Figure 24. The Relationship between the Lead−angle and the Delay of Output Current

The relationship between rotational speed and Lead−angle is shown in Figure 25. The optimum Lead−angle will vary by the motor characteristics so it is necessary to adjust the Lead−angle based on the motor in use.

Figure 25. Lead−angle Curve Image

The LV8316H has the following protection functions

• TSD (Thermal Shut Down) • UVLO (Under Voltage Lock Out)

• CLM (Current Limiter)

• OCP (Over Current Protection)

• Lock protection

The LV8316H can set the Lead−angle at maximum target rotational speed (TAG_H) and at minimum target rotational speed (TAG_L) by "DLDEG_H" and "DLDEG_L" individually.

These register have 8 bits D[7:0] in each and both MSBs define the direction of phase delay. When MSB sets to "0", the Lead−angle is set to minus value which means phase delay, that is, the output voltage commutation is delay than the Hall sensor signal. When MSB sets to 1, the Lead−angle is set to plus value which means phase advance, that is, the output voltage commutation is earlier than the Hall sensor signal. The resolution is approximately 0.175°. Hence, the adjustable range is from −22.225° to 22.225° expressed in the following equation.

Lmax =
$$
\frac{22.225}{127}
$$
 × DLDEG_H [deg]
Lmin = $\frac{22.225}{127}$ × DLDEG_L [deg]

where:

Lmax: Lead−angle at max. target rotational speed (TAG_H)

Lmin: Lead−angle at min. target rotational speed (TAG_L) Once DLDEG_H and DLDEG_L are set, the Lead−angle in other speed is set to interpolated and extrapolated value according to the rotational speed, even though the rotational speed is defined by $\text{FULL} = 1$.

PROTECTIONS

Table 15. UVLO TRUTH TABLE

Thermal Shutdown Protection (TSD)

When LV8316H's junction temperature rises to 180°C, TSD will activate and turns off high−side and low−side Power FET. Therefore, OUT1 and OUT2 pins will become high impedance and the coil current will shut off. When it falls under 140ºC, TSD will deactivate and motor will start to rotate.

When the TSD or Lock protection works, all of the internal FETs are turned off. When UVLO or CLM works, the output PWM is off and the motor goes to re−circulation mode.

Under Voltage Lock Out (UVLO)

When VCC voltage goes to low level (3.4 V), UVLO will activate and stop the motor. It is cleared when VCC voltage recovers over 3.6 V.

The TRUTH TABLE of UVLO is as shown in Table 15.

Lock Detection and Lock Protection

When the motor is locked, the heat is continuously generated because the IC keeps trying to rotate the motor.

The lock protection works to prevent such a heat generation by turning off the motor current. When a motor is locked in the steady rotation mode and IC doesn't detect the FG edge for more than 0.3 s which is equivalent to 50 rpm, the lock protection works (Figure [26\)](#page-18-0).

The lock protection signal can be output from FG pin by setting the register "TACHSEL". Please see Table [20.](#page-23-0) In this mode, the RD signal goes to "High", though it is "Low" at motor starts.

When the motor restarts and IC detects 4 phase changes at least (depends on rotation speed), the RD signal goes to "Low".

Figure 26. Timing Chart of the Lock Protection

Figure 27 shows the relationship between protection period and the number of protection times. 1st to 4th protection period take 3.5 s and $5th$ protection period takes 14 s. To reset the lock protection mode, Stop duty cycle must

be applied to the PWM input signal. To retry the motor rotation, Proper duty cycle must be applied to the PWM input signal.

Figure 27. The Relationship between Protection Time and Number of Times Protection

These protection periods and the number of protection times are applied in accordance with the internal counter. It will reset the counter if the duty−cycle which sets the motor speed to 0 rpm determined by "DUTY_L" and "DUTY_S" is entered during lock protection period (in either 3.5 sec or

14 sec). In this case, the lock protection counter will activate from the initial state starting from PWM Pos−Edge and protection period will start from 1st time as shown in Figure [28](#page-19-0) and Figure [29](#page-19-0).

Figure 29. Lock Protection Counter Reset during 14 sec Lock Protection Period

The lock protection period is changed by the condition of output signal. If the duty−cycle which sets motor speed to 0 rpm is input and the output signals are disappeared during the restart period in lock protection period as shown in light blue in Figure 30, the counter is not reset and the remaining

restart period is applied immediately when PWM Pos−Edge will be input as shown in pink in Figure 30. In this case, the protection period is not related to the internal lock protection timer and protection period is not fixed to 3.5 sec or 14 sec.

Figure 30. In Case of Having Changes in Protection Period

Current Limiter (CLM)

When the coil current becomes large, CLM will activate and then output will be in the re−circulation state. The current is monitored by internal sensing resistance and the threshold is 2.0 A (typ.).

There are three registers related to the current limiter function. The first one is CL_SKIP which can set the period of protection operation when CL is detected. The second one is CL_ASYNC. When "1" is set to this register while CL is active, synchronous rectification of the output becomes disabled. The third one is OCP_MASK which sets the masking time to ignore upper and lower FET's reverse recovery. See Table [20](#page-23-0) for more details.

Overcurrent Protection (OCP)

OCP monitors the coil current by internal sensing resistance and if it becomes larger than 2.5 A (typ) even if CLM is activated, OCP will activate and motor driver will stop.

Register called OCP_LAT_CLR allows to select behavior when OCP is activated. One is to keep the motor stopped until the next power on sequence, and the other one is to activate Lock protection mode. See Table [20](#page-23-0) for more details.

NONVOLATILE MEMORY

The LV8316H has internal nonvolatile memory which can store register values which define various parameters and settings. The stored register values will be reloaded at POR shown as Figure 31. LV8316H has also the communication mode. It allows user to modify register values, and to store them to the nonvolatile memory (Figure 31). It doesn't need the resistors as like the conventional models to set the various review In addition, PCB design becomes simpler.

Here is a list of the main configurable items.

• Max/Min rotational speed.

- Max/Min input duty−cycle.
- Lead−angle
- Soft start
- Speed control slope

Program/Erase to the memory is performed through a built−in register. Please note that Program/Erase is allowed for 10 times only. For more detail, please see the application note NVM Programming Procedure.

Figure 31. Image of Internal Register and Nonvolatile Memory

SERIAL INTERFACE

The LV8316H allows communication via UART (Universal Asynchronous Receiver Transmitter). Various parameter registers can be accessed through UART communication.

UART is one to one communication and the LV8316H doesn't support parallel access to the multiple devices, so be sure to turn on only the target devices.

The LV8316H provides two UART modes, a one−wire mode and a two−wire mode. In one−wire mode, the FG pin is used for both input and output. In two−wire mode, the FG pin is used as output and the PWM pin is used as input. The state of the TSL pin defines the UART mode as shown in Table 16.

Figure 32 shows the connection image of one−wire mode. The communication line FG should be open−drain type because it supports duplex mode. Therefore the communication pin of the MPU or CPU must be an

open−drain output. Figure 33 shows the connection image of two−wire mode. Please refer to the Application note [AND9761/D](https://www.onsemi.com/pub/Collateral/AND9761-D.PDF) for more detail.

Figure 32. Connection Image of One−wire Mode

Figure 33. Connection Image of Two−wire Mode

About the detail of communication protocol, please see the Application note, [AND9761/D.](https://www.onsemi.com/pub/Collateral/AND9761-D.PDF)

REGISTER MAP

Register MAP

Internal register map can be classified into four types as shown in Table 17.

- $\mathcal{L}_{\mathcal{A}}$ Read only
- Read/Write, User defined registers to be written to nonvolatile memory. $\mathcal{L}^{\mathcal{L}}$
- Read/Write \Box
- $\mathcal{L}_{\mathcal{A}}$ Write only (Auto clear)

Table 17. REG. MAP 1 (Address 0x000 – 0x0114)

Table 18. REG. MAP 2 (Address 0x0219)

Registers in the black cells do not exist. Therefore, these registers cannot be written and the read values are always zero. The bits with numeric values (0 or 1) must remain as−is.

There are some register addresses which contain both the bits stored in NVM and the bits not stored in NVM. Confirm the bit types to save the data to NVM.

REGISTER DESCRIPTION

Table 19. REGISTER ADDRESS 0x0000−0x0005 Register Description 1

COMMUNICTION ERROR

The Communication error is reported in the Register (Address 0x0219). Table 22 shows the error report functions.

				State after Error		
Address	Bit	DRVMODE	Error Description	Mode	Communication	Transferred Data
0x0219	D[6]	R/W Field Data Error	Non-zero value is written in the D[5:1] in R/W Field	Wait for the data from the master	Enable	In write mode; Nullified In read mode; No action
	D[5]	Time out Error	The delay between the fields in "Communication mode" is longer than 3 fields	"Standby"	Terminated	
	D[4]	Checksum Error	Checksum value is wrong in write mode	"Error"	Terminated	Nullified
	D[3]	Data Length Field parity Error	The parity in "Data Length Field" is wrong	"Error"	Terminated	Nullified
	D[2]	R/W Field parity Error	The parity in "R/W Field" is wrong	"Error"	Terminated	Nullified
	D[1]	Header Error	Header input is not correct	"Error"	Terminated	Nullified
	D[0]	Framing Error	The signal pin is "Low" state in Stop bits	"Error"	Terminated	Nullified

Table 22. ERROR REPORT DESCRIPTION

When "Time out error" posts "1" in D[5] of register 0x0219, the LV8316H goes into standby mode.

If the data length is long and the "Time out Error" is happened during the Register write, the data with the correct "Checksum" transferred before the "Time out Error" is stored in register, then the LV8316H goes to "Standby mode".

When "Checksum error" posts "1" in D[4] of Register 0x0219 while in the Write mode, the LV8316H goes into Error mode and the communication is terminated. In this case, the transferred data is discarded but the data with correct "Checksum" transferred before the "Checksum error" is stored in the register.

Other errors, except for "R/W Field Data Error" also write "1" in the specified register and the LV8316H goes to "Error mode" as well. To recover from "Error mode", the communication pin should be kept "High" for longer than the time corresponding to 4 "Fields", then the LV8316H goes to "Standby mode" automatically despite of the status of error register.

Each error register keeps the error bit until the master reads the error register.

Reading Reg.0x0219 as 1byte will clear the error bits. Multiple read will not clear the error bits.

It is recommended to read the error register after every transaction to confirm that the communication is completed successfully.

Figure [34](#page-28-0) shows the state diagram. Refer to the Application note **AND9761/D** as well for more information regarding the communication.

Figure 34. State Transition Diagram of Each Error

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NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION b DOES NOT INCLUDE DAMBAR
PROTRUSION. ALLOWABLE PROTRUSION SHALL BE **ECONDUM MAXIMUM MATERIAL CONDITION.**
DAMBAR CANNOT BE LOCATED ON THE LOWER RADI-
	- US OF THE FOOT. MINIMUM SPACE BETWEEN PRO-TRUSION AND ADJACENT LEAD IS 0.07. 4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION D IS DETERMINED AT DATUM H.
	- 5. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSION E1 IS DETERMINED AT DATUM H.
	- 6. DATUMS A AND B ARE DETERMINED AT DATUM H. 7. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE
	- PACKAGE BODY. 8. SECTION B−B TO BE DETERMINED AT 0.10 TO 0.25 mm FROM THE LEAD TIP.

GENERIC MARKING DIAGRAM*

*This information is generic. Please refer to device data sheet for actual part marking. device data sheet for actual part marking
Pb−Free indicator, "G" or microdot " ■", may or may not be present.

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